



Customer Information Notification

201705006I

Issue Date: 01-Jun-2017

Effective Date: 02-Jun-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



Change Category

☐ Wafer Fab Process	☒ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

LQFP 10x10 High Density
Lead Frame Conversion
for NXP ATTJ Assembly

Information Notification

NXP Semiconductors announces the LQFP 10x10 64ld lead frame conversion from standard matrix configuration to High Density configuration for the NXP ATTJ, Tianjin, China assembled devices associated with this notification. Lead frame strip configuration quantity increases from 16 units per strip to 80 units per strip for manufacturing standardization and capacity / utilization improvement. No change to lead frame materials, flag size or flag shape. Visual change only to package corner shape - from current one beveled / chamfered package corner to new four beveled / chamfered package corners. Per LQFP case outline drawings, "Exact shape of each corner is optional", not defined, and therefore considered a minor change.

Customer Information Notification, CIN 201705006I, is issued to ensure no customer manufacturing disruption upon NXP implementation of LQFP 10x10 high density lead frame conversion as relayed in the notification Effective Date. Upon the Effective Date, LQFP products will begin a ramped implementation of new high density lead frame, with the resulting additional package beveled / chamfered corners.

Please see attached change summary presentation for details.

Why do we issue this Information Notification

LQFP 10x10 high density lead frame conversion is required for manufacturing standardization and capacity / utilization improvement.

Identification of Affected Products

Product identification does not change

Impact

With the exception of additional package beveled / chamfered corners, no other impact to form, fit, function or reliability.

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Ze Shi
Position Assembly Engineering
e-mail address ze.shi@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line
MC33816AE	935311309557	MC33816AE	eMGS625D	HLQFP64	RFS	BL Advanced Automotive Analog
MCZ33789BAE	935320323557	MCZ33789BAE	Air Bag System IC	HLQFP64	RFS	BL Advanced Automotive Analog
MC9S12XS64CAE	935317069557	MC9S12XS64CAE	"16BIT 128K FLASH, 64LQFP"	QFP64	RFS	BL Auto Micro Processors
MC34SB0800AE	935318335557	MC34SB0800AE	VAPS 8 VALVES	HLQFP64	RFS	BL Advanced Automotive Analog
S912ZVML31F1WKH	935312981557	S912ZVML31F1WKH	S12Z core,32K Flash,64LQ	HLQFP64	RFS	BL Auto Micro Processors
S912ZVCA19F0MKH	935317743557	S912ZVCA19F0MKH	S12Z,64LQFP-EP,192K FLAS	HLQFP64	RFS	BL Auto Micro Processors
MC34SB0800AER2	935318335528	MC34SB0800AE	VAPS 8 VALVES	HLQFP64	RFS	BL Advanced Automotive Analog